



Material Content Data Sheet



Sales Product Name		BCW 68F E6327		Issued		29. August 2013		
MA#		MA000405660						
Package		PG-SOT23-3-3		Weight*		8.71 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		37	
	noble metal	gold	7440-57-5	0.032	0.37		3687	
	inorganic material	silicon	7440-21-3	0.110	1.26	1.63	12596	16320
leadframe	non noble metal	nickel	7440-02-0	1.142	13.11		131129	
	non noble metal	iron	7439-89-6	1.578	18.11	31.22	181083	312213
wire	noble metal	gold	7440-57-5	0.019	0.22	0.22	2208	2208
encapsulation	organic material	carbon black	1333-86-4	0.089	1.02		10237	
	inorganic material	antimonytrioxide	1309-64-4	0.134	1.54		15355	
	plastics	brominated resin	-	0.167	1.92		19194	
	plastics	epoxy resin	-	1.393	16.00		159952	
	inorganic material	silicondioxide	60676-86-0	3.790	43.50	63.98	435072	639809
leadfinish	non noble metal	tin	7440-31-5	0.150	1.72	1.72	17176	17176
plating	noble metal	silver	7440-22-4	0.107	1.23	1.23	12274	12274
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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